EC4SM-25.000M

Vibration



EC4SM

Series 4.0mm Epoxy Base SMD Crystal Frequency Tolerance/Stability ±50ppm at 25°C, ±100ppm over 0°C to +70°C

Mode of Operation AT-Cut Fundamental

-25.000M

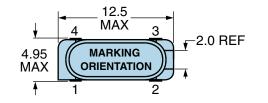
L Nominal Frequency 25.000MHz

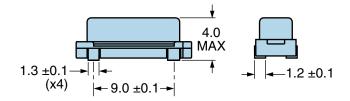
Load Capacitance 18pF Parallel Resonant

| ELECTRICAL SPECIFICATIONS | | | |
|---|--|--|--|
| 25.000MHz | | | |
| ±50ppm at 25°C, ±100ppm over 0°C to +70°C | | | |
| ±5ppm/year Maximum | | | |
| 18pF Parallel Resonant | | | |
| 7pF Maximum | | | |
| 40 Ohms Maximum | | | |
| AT-Cut Fundamental | | | |
| 1mWatts Maximum | | | |
| -40°C to +85°C | | | |
| 500 Megaohms Minimum at 100Vdc | | | |
| ENVIRONMENTAL & MECHANICAL SPECIFICATIONS | | | |
| MIL-STD-883, Method 1014 Condition A | | | |
| MIL-STD-883, Method 1014 Condition C | | | |
| MIL-STD-202, Method 213 Condition C | | | |
| MIL-STD-202, Method 210 | | | |
| MIL-STD-202, Method 215 | | | |
| MIL-STD-883, Method 2003 | | | |
| MIL-STD-883, Method 1010 | | | |
| | | | |

MECHANICAL DIMENSIONS (all dimensions in millimeters)

MIL-STD-883, Method 2007 Condition A





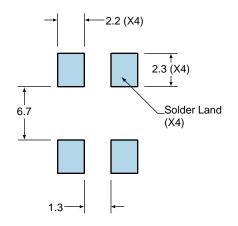
| PIN | CONNECTION |
|------|-----------------------------------|
| 1 | Connected to Pin 4 and to Crystal |
| 2 | Connected to Pin 3 and to Crystal |
| 3 | Connected to Pin 2 and to Crystal |
| 4 | Connected to Pin 1 and to Crystal |
| LINE | MARKING |
| | |
| 1 | E25.000 E=Ecliptek Designator |
| | |

EC4SM-25.000M



Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

EC4SM-25.000M



Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 225°C

| T _s MAX to T _L (Ramp-up Rate) | 5°C/second Maximum |
|---|----------------------------|
| Preheat | |
| - Temperature Minimum (T _s MIN) | N/A |
| - Temperature Typical (T _s TYP) | 150°C |
| - Temperature Maximum (T _s MAX) | N/A |
| - Time (t _s MIN) | 30 - 60 Seconds |
| Ramp-up Rate (T _L to T _P) | 5°C/second Maximum |
| Time Maintained Above: | |
| - Temperature (T∟) | 150°C |
| - Time (t _L) | 200 Seconds Maximum |
| Peak Temperature (T _P) | 225°C Maximum |
| Target Peak Temperature (T _P Target) | 225°C Maximum 2 Times |
| Time within 5°C of actual peak (t _p) | 80 seconds Maximum 2 Times |
| Ramp-down Rate | 5°C/second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.